

## **Driving Moore's Law through Process and Packaging Innovations**

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### <Abstract>

Moore's Law has been the guiding principle for the semiconductor industry for more than 50 years. Continuing to drive Moore's Law scaling requires integrating new features from every aspect of the compute platform. In this presentation we will discuss Intel's process innovations implemented on 10nm including recently introduced SuperFin Technology which represents the largest single intranode enhancement in the company's history. Also, we will discuss advanced packaging technology such as EMIB (Embedded Multi-Die Interconnect Bridge), Foveros, Hybrid Bonding, Co-EMIB and ODI (Omni Directional Interconnect), as continuing to advance Moore's Law in a new dimension.

### <Biography>

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Naoki Kitano joined Intel K.K. in 1994. He has worked on a wide range of projects: Flash process integration, Mask technology development, Semiconductor equipment & material supply chain management, and Package substrate equipment. Since 2009, he has been responsible for Intel External Programs in Japan and engaged in management of several programs including the EIDEC program.